IN THE ABSTRACT:

(N.E.)
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Please add the following abstract paragraph to the end of the patent application:

The present invention introduces several methods for implementing arbitrary angle wiring layers for integrated circuit manufacture with simulated Euclidean wiring. Entire routing layers may be implemented with arbitrary angle preferred wiring using simulated Euclidean wiring. In a first embodiment, the arbitrary angle wiring layers are created by routing arbitrary angle wires created from a selected ratio alternating segments of horizontal interconnect wire segments and vertical interconnect wire segments. In another embodiment, the arbitrary angle wiring layers are created by routing arbitrary angle wires created from a selected ratio alternating segments of horizontal interconnect wire segments and diagonal interconnect wire segments.

IN THE CLAIMS:

Please amend the claims in the above-identified patent application to appear as follows:

Please cancel claims 1 to 58.

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